THE DATASHEET OF

VND10N06TR-E

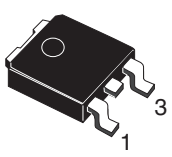
VND10N06
VND10N06-1

"OMNIFET"
fully autoprotected Power MOSFET

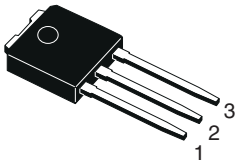
Features

Max on-state resistance (per ch.)	$R_{DS(on)}$	0.3Ω
Current limitation (typ)	I_{lim}	10A
Drain-Source clamp voltage	V_{CLAMP}	60V

- Linear current limitation
- Thermal shutdown
- Short circuit protection
- Integrated clamp
- Low current drawn from input pin
- Logic level input threshold
- ESD protection
- Schmitt trigger on input
- High noise immunity



DPAK
TO-252



IPAK
TO-251

Description

The VND10N06 and VND10N06-1 are monolithic devices designed in STMicroelectronics VIPower M0-2 technology, intended for replacement of standard Power MOSFETs in DC to 50KHz applications. Built in thermal shutdown, linear current limitation and overvoltage clamp protect the chip in harsh environments.

Table 1. Device summary

Package	Order codes	
	Tube	Tape and reel
DPAK	VND10N06	VND10N06TR
IPAK	VND10N06-1	

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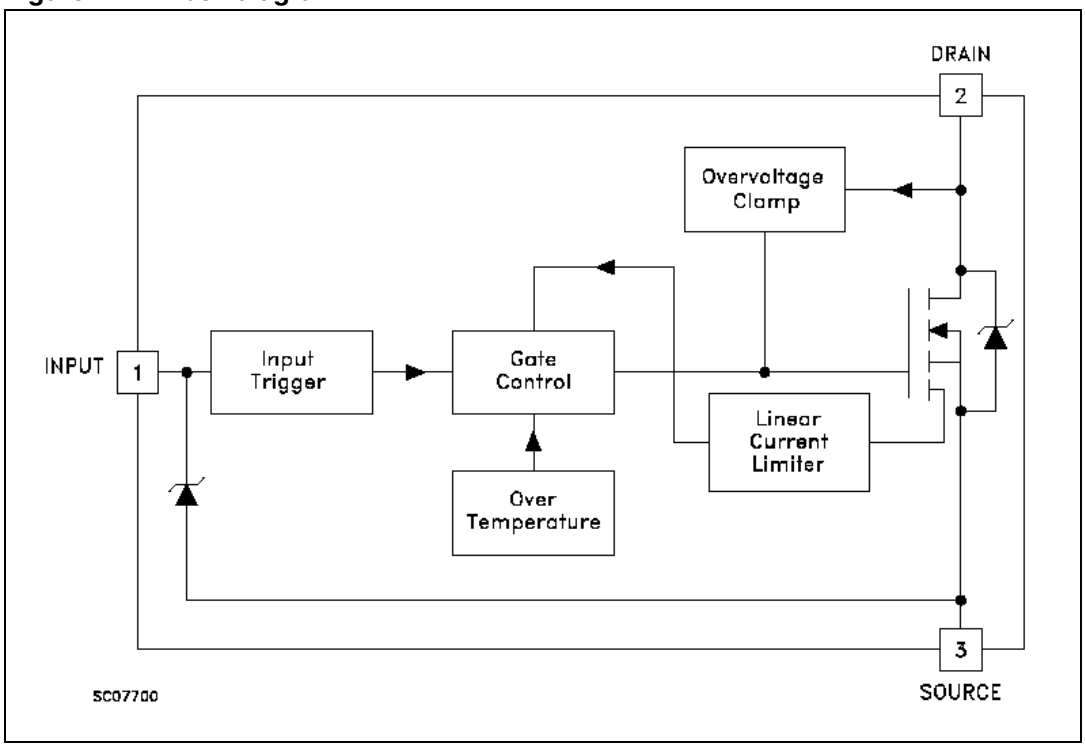
1 Block diagram and pin description

Figure 1. Block diagram



2 Electrical specifications

2.1 Absolute maximum ratings

Stressing the device above the rating listed in the “Absolute maximum ratings” table may cause permanent damage to the device. These are stress ratings only and operation of the device at these or any other conditions above those indicated in the operating sections of this specification is not implied. Exposure to Absolute maximum rating conditions for extended periods may affect device reliability. Refer also to the STMicroelectronics SURE program and other relevant quality document.

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DSn}	Drain-Source voltage (V_{in} = 0V)	Internally clamped	V
V_{INn}	Input voltage	Internally clamped	V
I_{in}	Input current	± 20	mA
I_{Dn}	Drain current	Internally limited	A
I_{Rn}	Reverse DC output current	- 15	A
V_{ESD}	Electrostatic discharge (R = 1.5KΩ, C = 100pF)	4000	V
P_{tot}	Total dissipation at T_c = 25°C	35	W
T_j	Operating junction temperature	Internally limited	°C
T_c	Case operating temperature	Internally limited	°C
T_{stg}	Storage temperature	- 55 to 150	°C

2.2 Thermal data

Table 3. Thermal data

Symbol	Parameter	Max. value	Unit
$R_{thj\text{-}case}$	Thermal resistance junction-case	3.5	°C/W
$R_{thj\text{-}amb}$	Thermal resistance junction-ambient	100	°C/W

2.3 Electrical characteristics

T_{case} = 25 °C unless otherwise stated.

Table 4. Off

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_{CLAMP}	Drain-Source clamp voltage	V_{IN} = 0V; I_D = 200mA	50	60	70	V
V_{IL}	Input low level voltage	I_D = 100 µA; V_{DS} = 16 V			1.5	V
V_{IH}	Input high Level voltage	R_L = 27Ω; V_{DD} = 16 V V_{DS} = 0.5 V	3.2			V
I_{ISS}	Supply current from input pin	V_{DS} = 0V; V_{IN} = 5V		150	300	µA
V_{INCL}	Input-Source reverse clamp voltage	I_{IN} = -1mA I_{IN} = 1mA	-1 8		-0.3 11	V V
I_{DSS}	Zero input voltage drain current (V_{IN} = 0V)	V_{DS} = 50V; V_{IN} = V_{IL}; V_{DS} < 35V; V_{IN} = V_{IL}			250 100	µA µA

Table 5. Switching(1)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	V_{DD} = 16V; I_D = 1A V_{gen} = 7V; R_{gen} = 10Ω (see *Figure 2*)		1100	1600	ns
t_r	Rise time			550	900	ns
$t_{d(off)}$	Turn-off delay time			200	400	ns
t_f	Fall time			100	200	ns
$t_{d(on)}$	Turn-on delay time	V_{DD} = 16V; I_D = 1A V_{gen} = 7V; R_{gen} = 1000Ω (see *Figure 2*)		1.2	1.8	µs
t_r	Rise time			1	1.5	µs
$t_{d(off)}$	Turn-off delay time			1.6	2.3	µs
t_f	Fall time			1.2	1.8	µs
$(di/dt)_{on}$	Turn-on current slope	V_{DD} = 16V; I_D = 1A V_{in} = 7V; R_{gen} = 10Ω		1.5		A/µs
Q_i	Total input charge	V_{DD} = 12V; I_D = 1A; V_{IN} = 7V		13		nC

1. Parameters guaranteed by design / characterization.

Table 6. On(1)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$R_{DS(on)}$	Static Drain-Source on resistance	V_{IN} = 7V; I_D = 1 A; T_j < 125 °C		0.15	0.3	Ω

1. Pulsed: pulse duration = 300µs, duty cycle 1.5%.

Table 7. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{OSS}	Output capacitance	V_{DS} = 13V; f = 1MHz; V_{IN} = 0V		350	500	pF

Table 8. Source Drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_{SD} (1)	Forward on voltage	I_{SD} = 1 A; V_{IN} = V_{IL}		0.8	1.6	V
t_{rr} (2)	Reverse recovery time	I_{SD} = 1A; di/dt = 100 A/µs V_{DD} = 30V; T_j = 25°C (see *Figure 4*)		125		ns
Q_{rr} (2)	Reverse recovery charge			0.22		µC
I_{RRM} (2)	Reverse recovery current			3.5		A

1. Pulsed: pulse duration = 300µs, duty cycle 1.5%.
2. Parameters guaranteed by design / characterization.

Table 9. Protections (-40°C < T_j < 150°C, unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{lim}	Drain current limit	V_{IN} = 7V; V_{DS}=13V	6	10	15	A
t_{dlim} (1)	Step response current limit	V_{IN} = 7 V; V_{DS} step from 0 to 13V		12	20	µs
T_{jsh} (1)	Overtemperature shutdown		150			°C
T_{jrs} (1)	Overtemperature reset		135			°C
E_{as} (1)	Single pulse avalanche energy	Starting T_j = 25°C; V_{DD} = 24V V_{IN} = 7V R_{gen} = 1kΩ; L = 10mH	250			mJ

1. Parameters guaranteed by design / characterization.

Figure 2. Switching waveforms

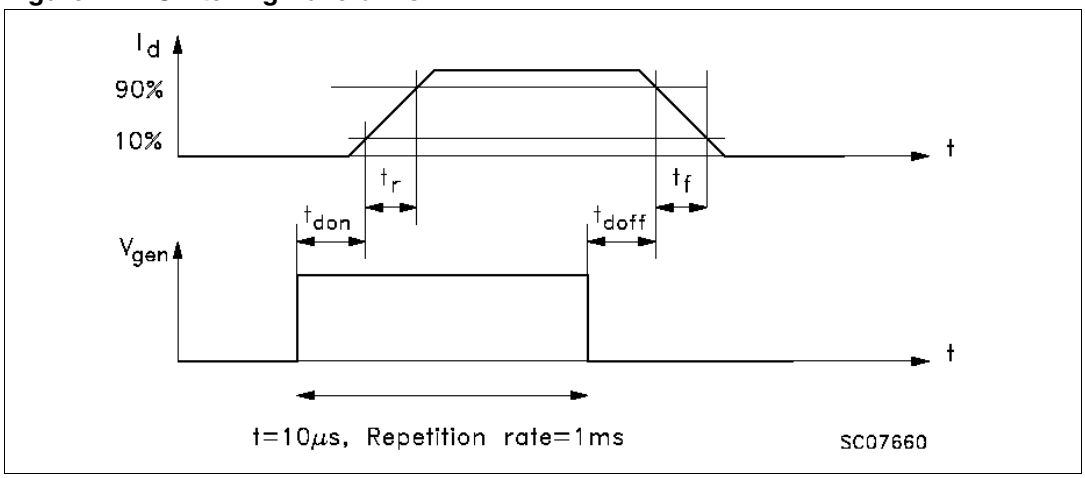


Figure 3. Switching time test circuit for resistive load

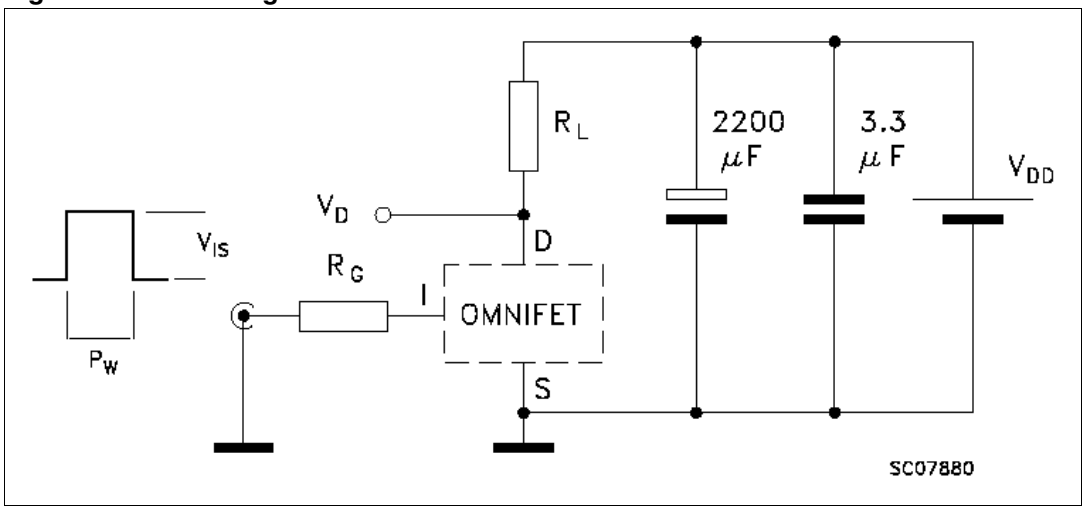


Figure 4. Test circuit for inductive load switching and diode recovery time

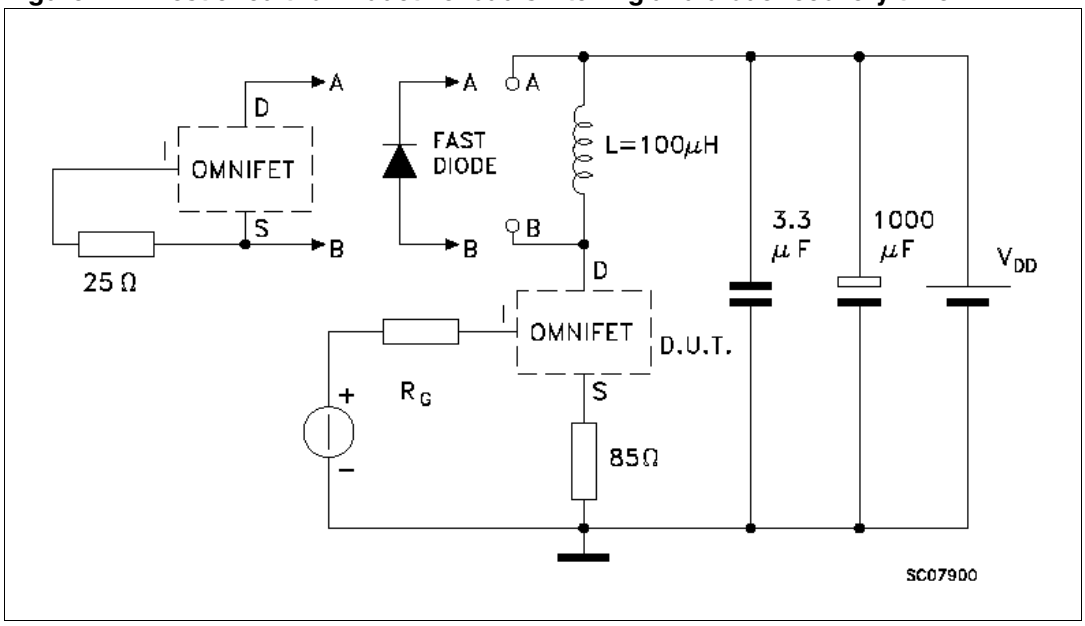


Figure 5. Unclamped inductive load test circuits

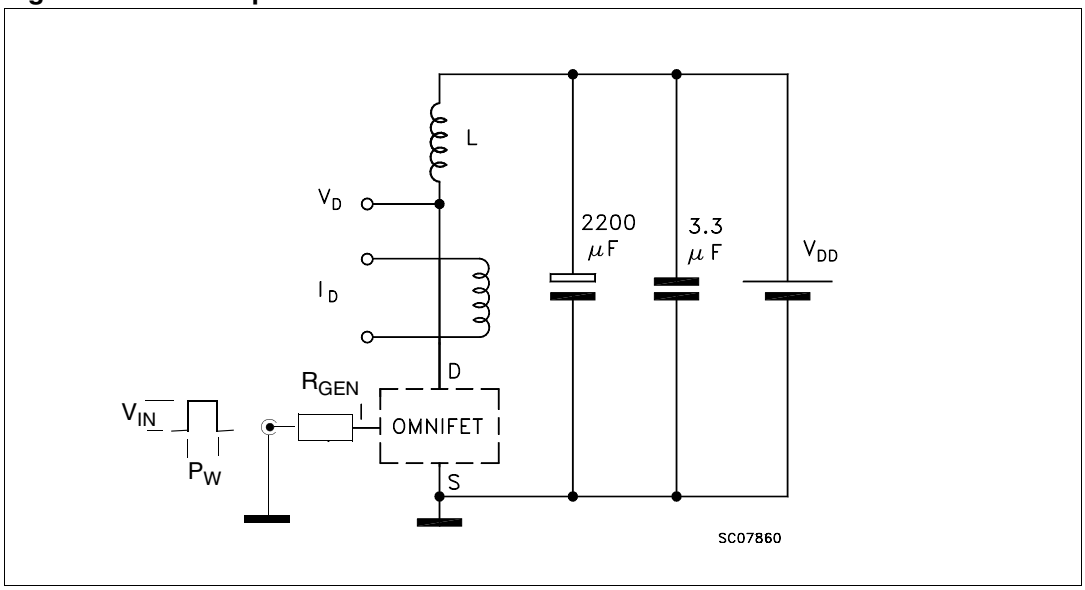


Figure 6. Input charge test circuit

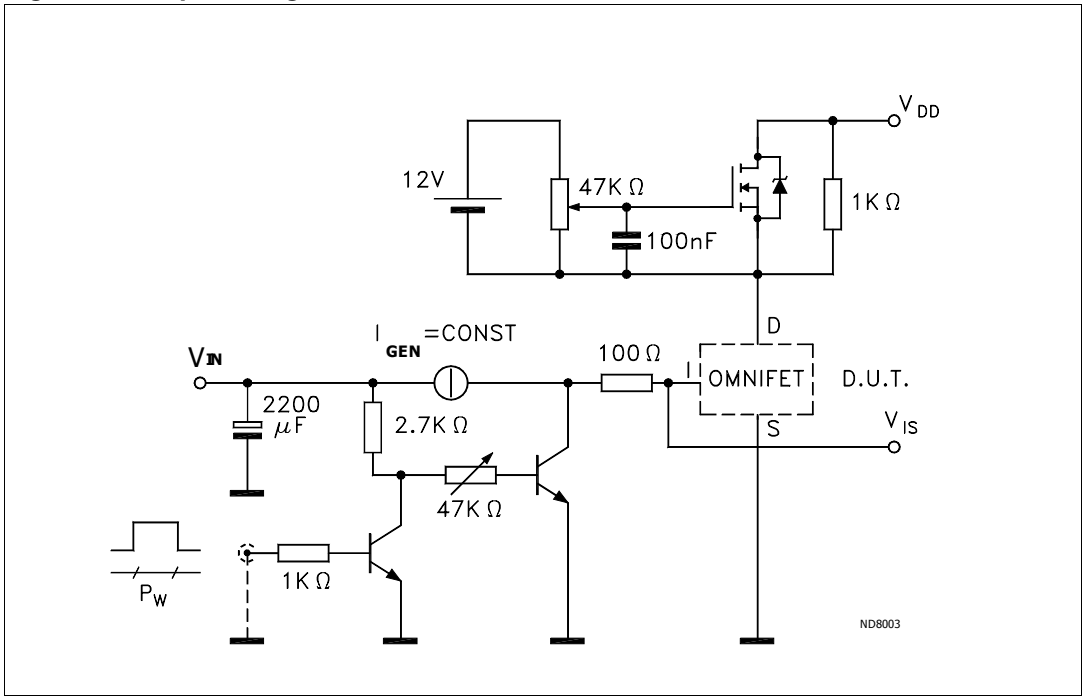
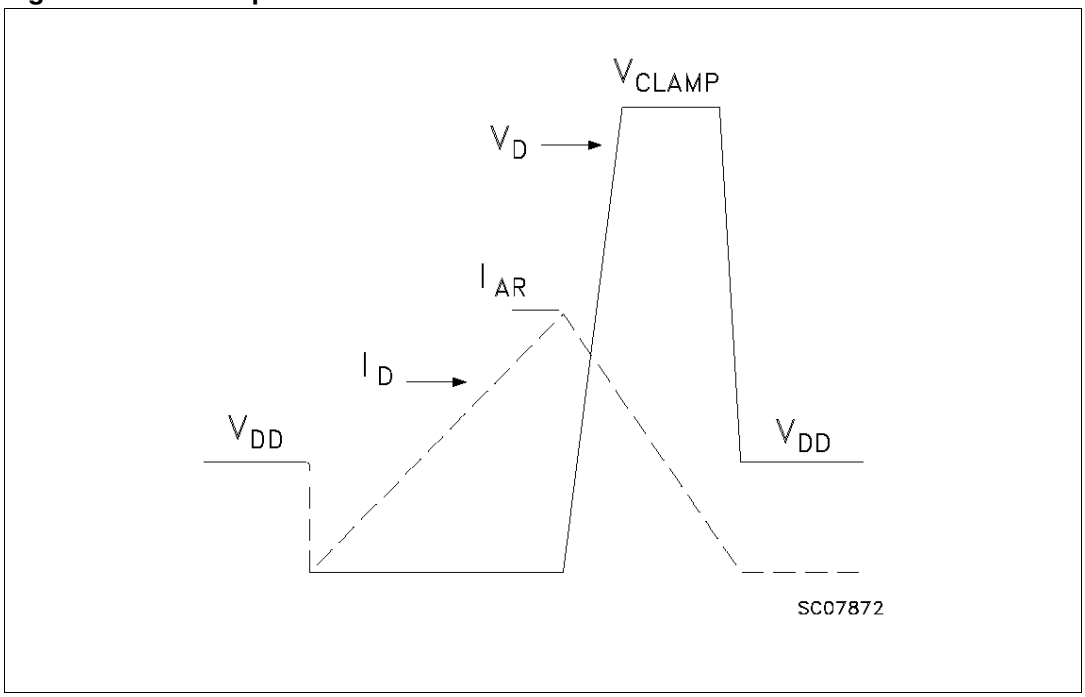


Figure 7. Unclamped inductive waveforms



2.4 Electrical characteristics curves

Figure 8. Static Drain-Source on resistance (V_{IN} = 3.5V)

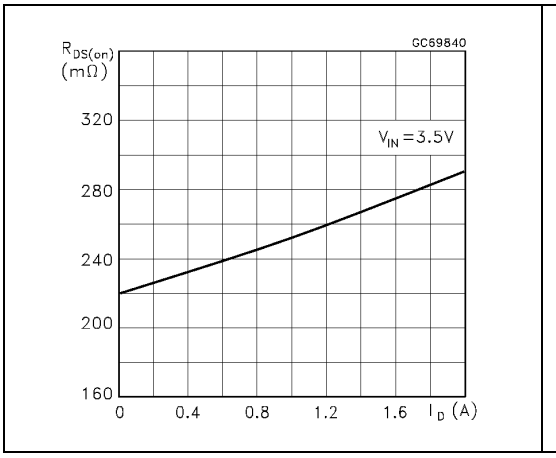


Figure 9. Static Drain-Source on resistance (V_{IN} = 5V)

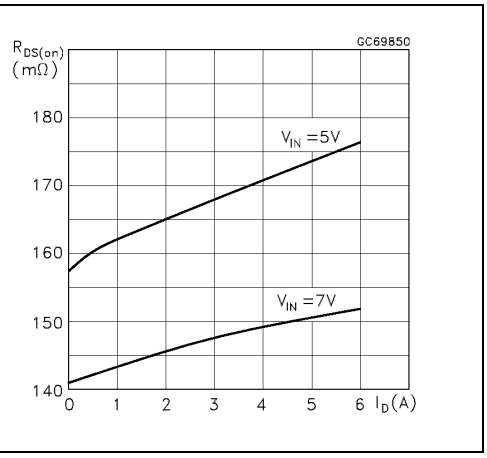


Figure 10. Derating curve

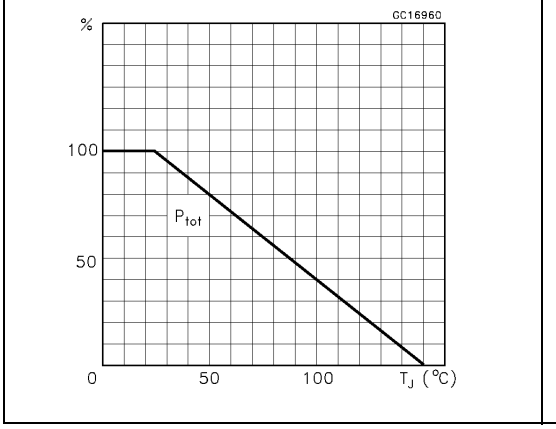


Figure 11. Static Drain-Source on resistance vs. input voltage

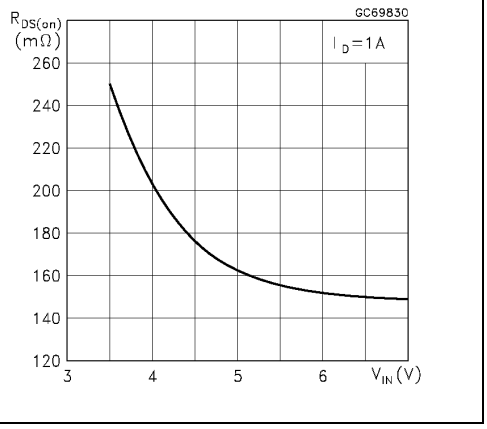


Figure 12. Current limit Vs. junction temperature

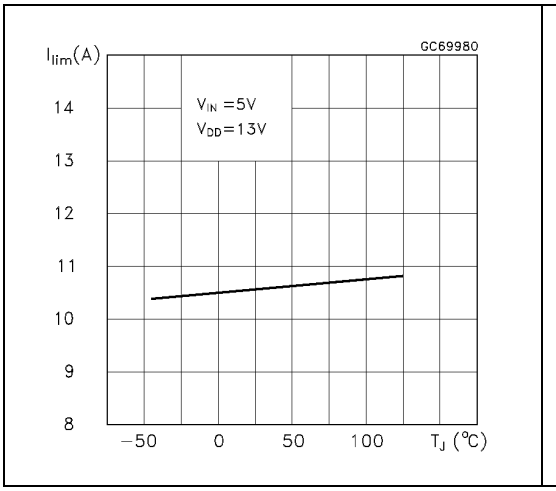


Figure 13. Source-Drain diode voltage Vs. junction temperature

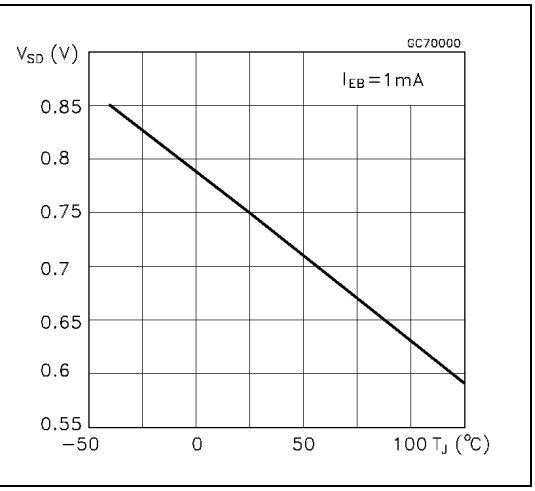


Figure 14. Step response current limit

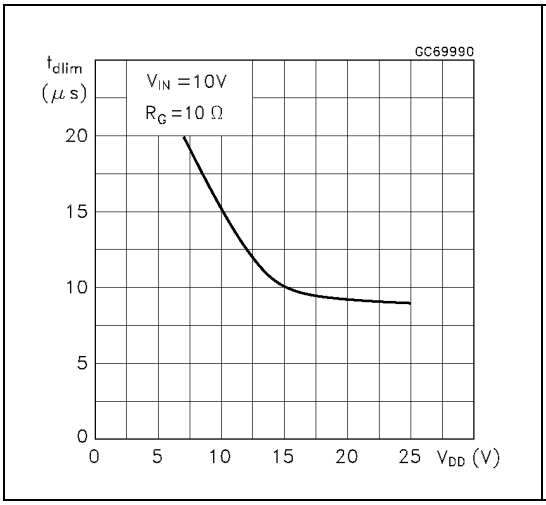


Figure 15. Switching time resistive load

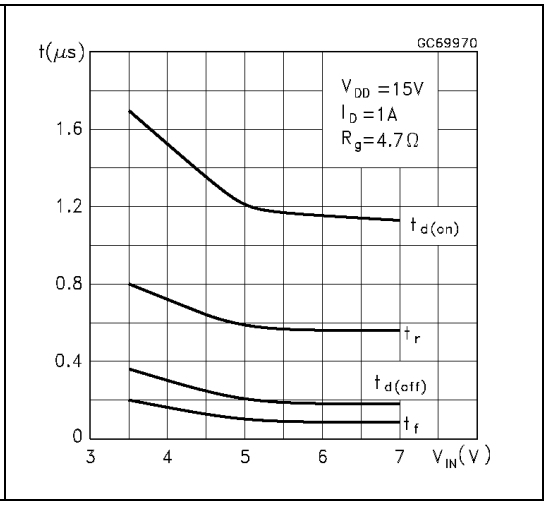


Figure 16. Turn-on current slope (V_{IN} = 3.5V)

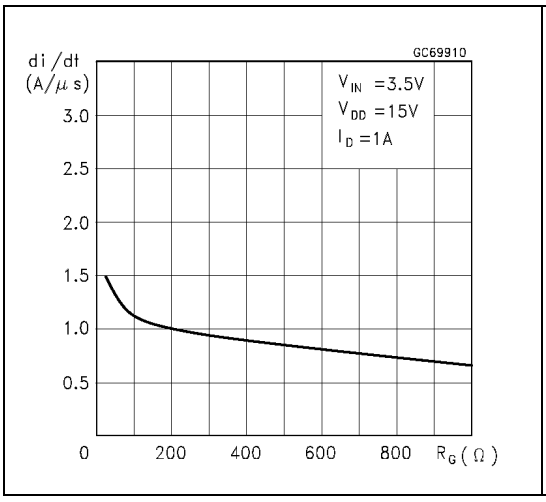


Figure 17. Turn-on current slope (V_{IN} = 7V)

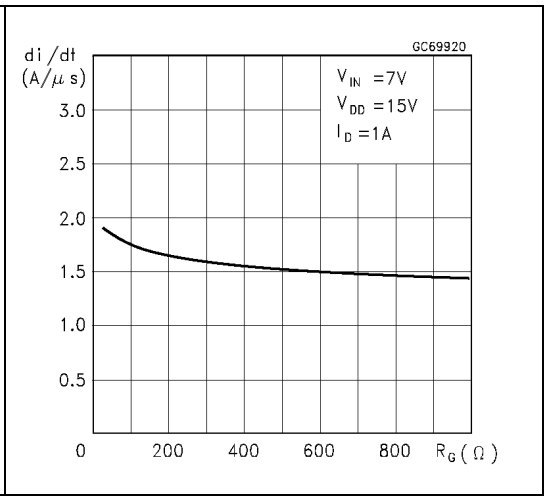


Figure 18. Input voltage Vs. input charge

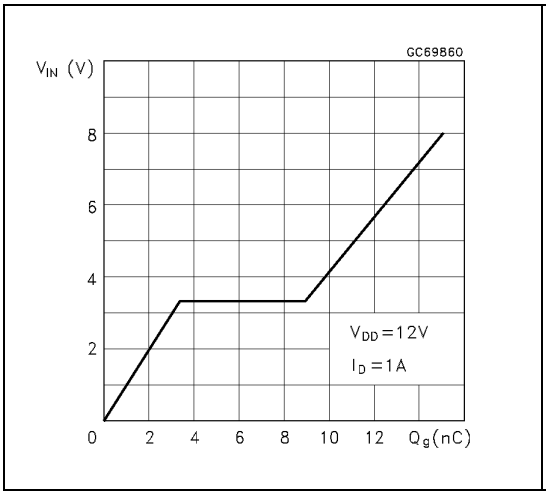


Figure 19. Turn-off Drain-Source voltage slope

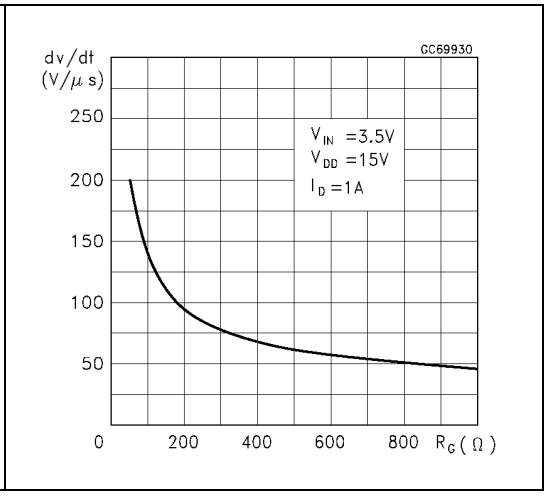


Figure 20. Turn-off Drain-Source voltage slope

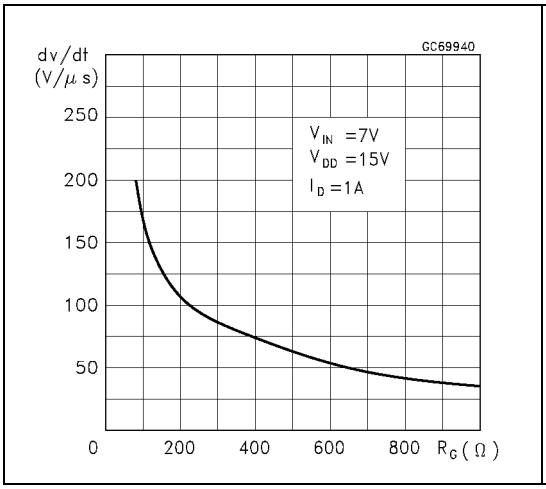


Figure 21. Capacitance variations

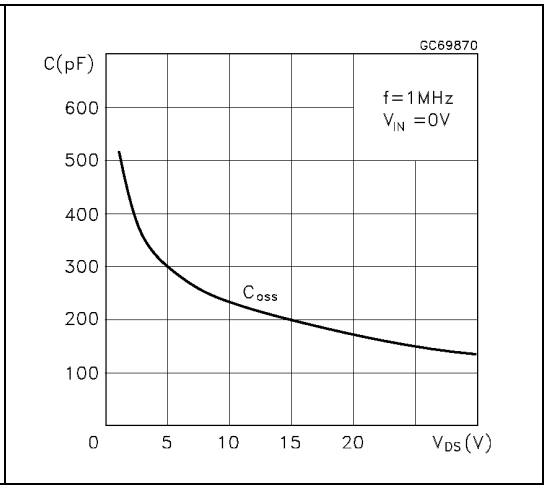


Figure 22. Switching time resistive load

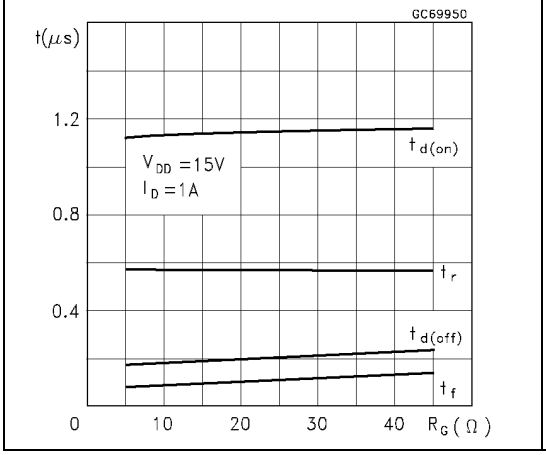


Figure 23. Normalized on resistance Vs. temperature (V_{IN} = 7V)

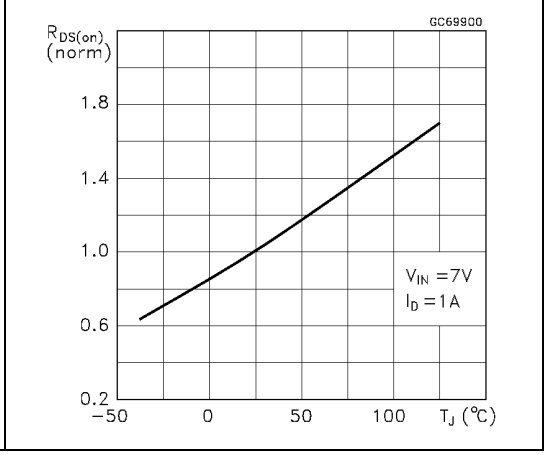


Figure 24. Output characteristics

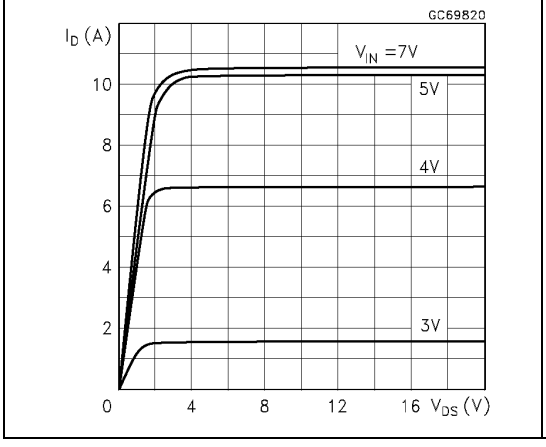


Figure 25. Normalized on resistance Vs. temperature (V_{IN} = 3.5V)

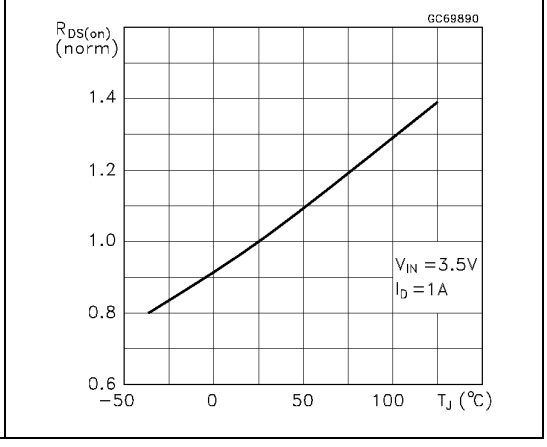
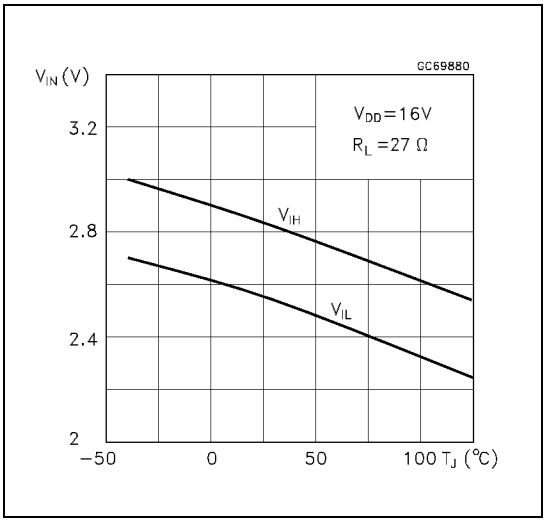


Figure 26. Normalized input threshold voltage Vs. temperature



3 Protection features

During normal operation, the INPUT pin is electrically connected to the gate of the internal power MOSFET through a low impedance path as soon as $V_{IN} > V_{IH}$.

The device then behaves like a standard power MOSFET and can be used as a switch from DC to 50KHz. The only difference from the user's standpoint is that a small DC current I_{ISS} flows into the INPUT pin in order to supply the internal circuitry.

During turn-off of an unclamped inductive load the output voltage is clamped to a safe level by an integrated Zener clamp between DRAIN pin and the gate of the internal Power MOSFET.

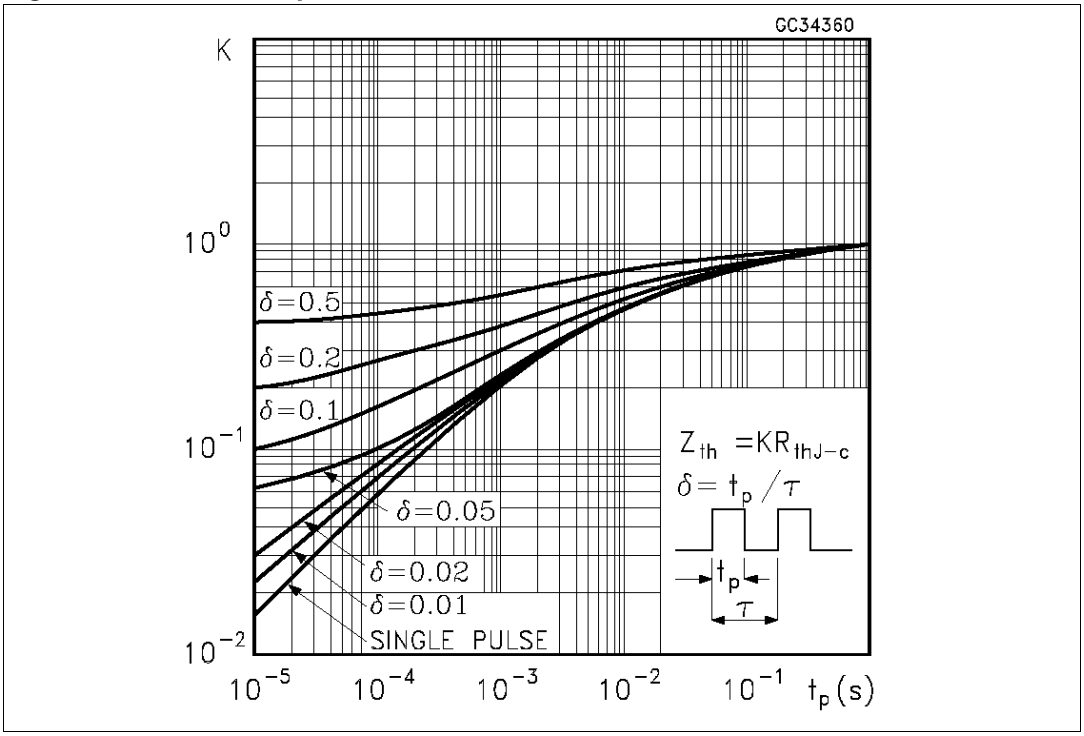
In this condition, the Power MOSFET gate is set to a voltage high enough to sustain the inductive load current even if the INPUT pin is driven to 0V. The device integrates an active current limiter circuit which limits the drain current ID to Ilim whatever the INPUT pin Voltage.

When the current limiter is active, the device operates in the linear region, so power dissipation may exceed the heatsinking capability. Both case and junction temperatures increase, and if this phase lasts long enough, junction temperature may reach the overtemperature threshold T_{jsh}.

If T_j reaches T_{jsh}, the device shuts down whatever the INPUT pin voltage. The device will restart automatically when T_j has cooled down to T_{jrs}.

4 Thermal data

Figure 27. Thermal impedance for DPAK / IPAK



5 Package and packing information

5.1 ECOPACK® packages

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

5.2 DPAK mechanical data

Figure 28. DPAK package dimensions

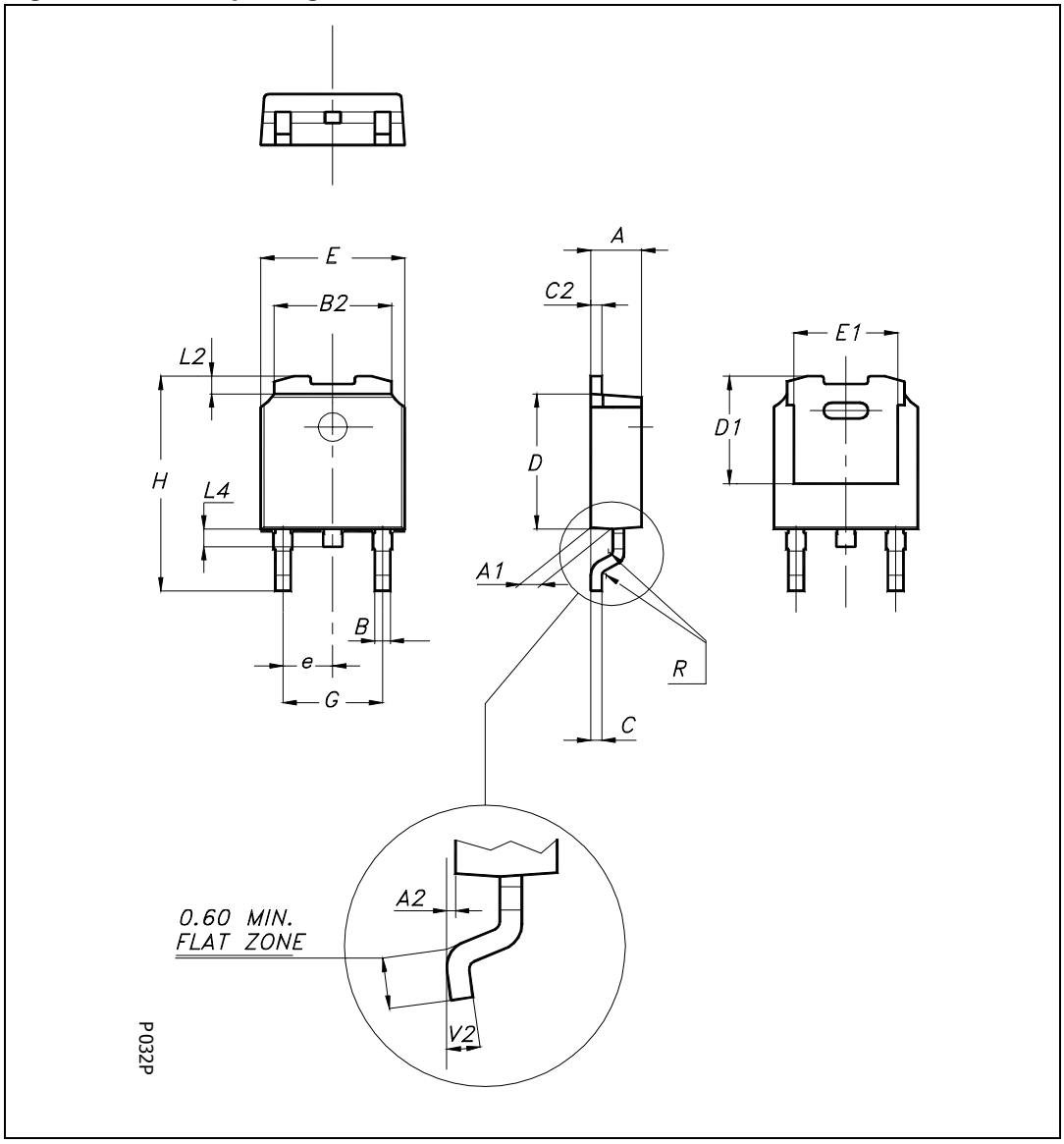


Table 10. DPAK mechanical data

Dim.	Millimeters		
	Min.	Typ.	Max.
A	2.20		2.40
A1	0.90		1.10
A2	0.03		0.23
B	0.64		0.90
B2	5.20		5.40
C	0.45		0.60
C2	0.48		0.60
D	6.00		6.20
D1		5.1	
E	6.40		6.60
E1		4.7	
e		2.28	
G	4.40		4.60
H	9.35		10.10
L2		0.8	
L4	0.60		1.00
R		0.2	
V2	0°	8°	
Package weight	Gr. 0.29		

5.3 IPAK mechanical data

Figure 29. IPAK mechanical data and package outline

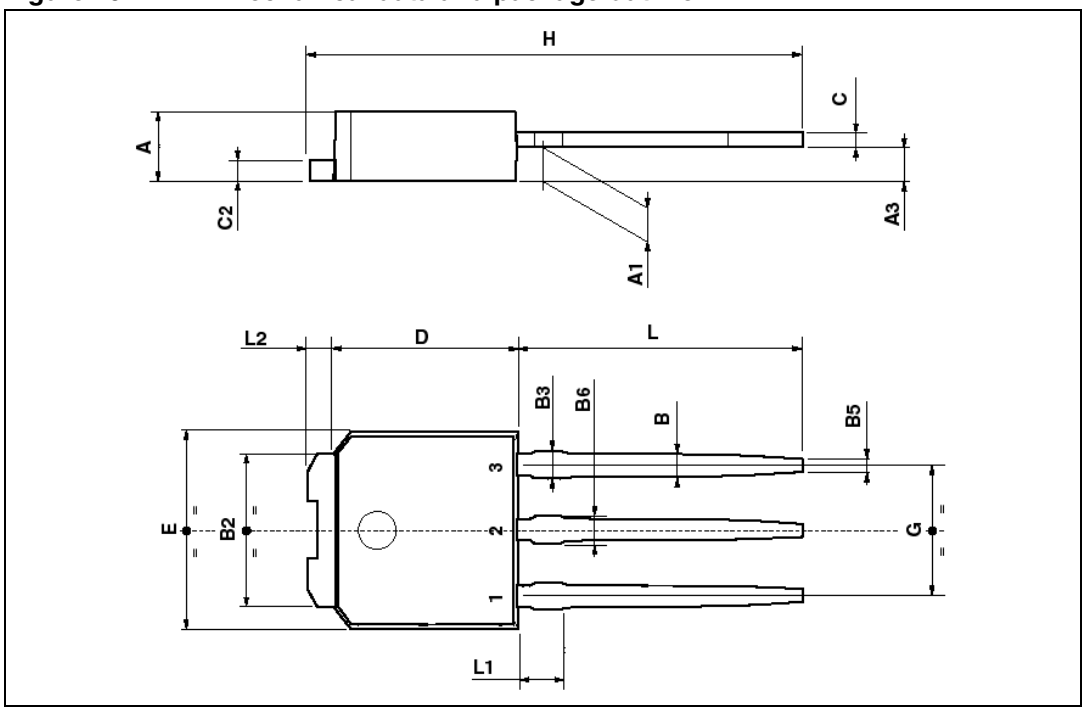


Table 11. IPAK mechanical data

Symbol	Millimeters		
	Min.	Typ.	Max.
A	2.2		2.4
A1	0.9		1.1
A3	0.7		1.3
B	0.64		0.9
B2	5.2		5.4
B3			0.85
B5		0.3	
B6			0.95
C	0.45		0.6
C2	0.48		0.6
D	6		6.2
E	6.4		6.6
G	4.4		4.6
H	15.9		16.3
L	9		9.4
L1	0.8		1.2
L2		0.8	1

5.4 DPAK packing information

The devices can be packed in tube or tape and reel shipments (see the *Device summary on page 1*).

Figure 30. DPAK footprint

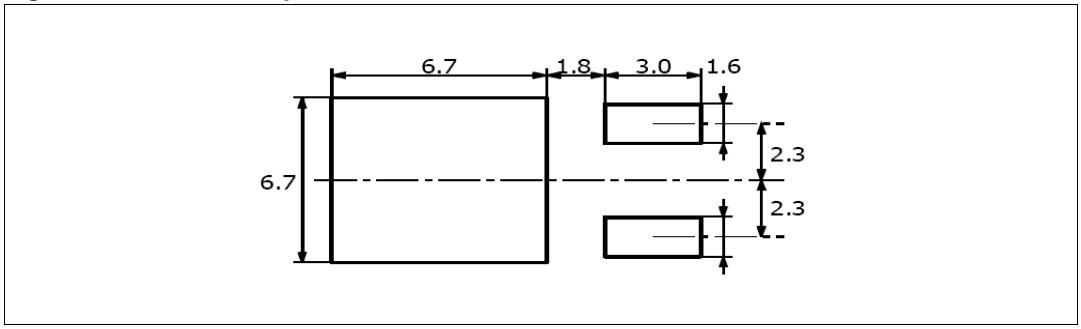
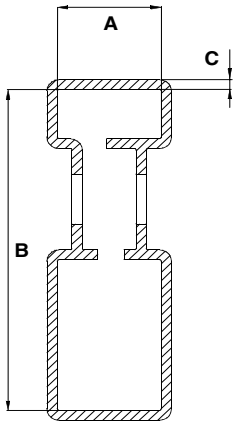


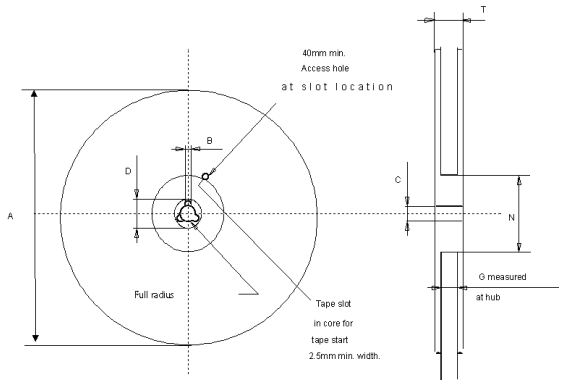
Figure 31. DPAK tube shipment (no suffix)



Base Q.ty	75
Bulk Q.ty	3000
Tube length (± 0.5)	532
A	6
B	21.3
C (± 0.1)	0.6

All dimensions are in mm.

Figure 32. DPAK tape and reel shipment (suffix “TR”)



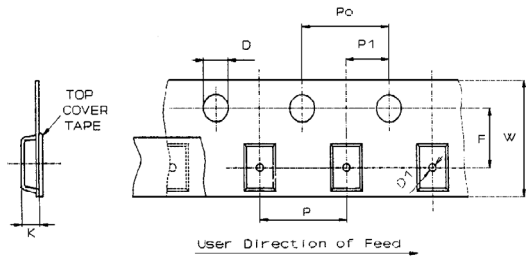
Reel dimensions

Base Q.ty	2500
Bulk Q.ty	2500
A (max)	330
B (min)	1.5
C (± 0.2)	13
F	20.2
G (+ 2 / -0)	16.4
N (min)	60
T (max)	22.4

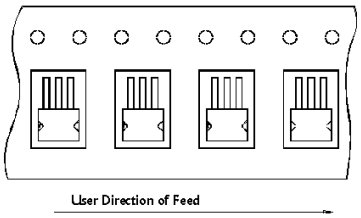
Tape dimensions

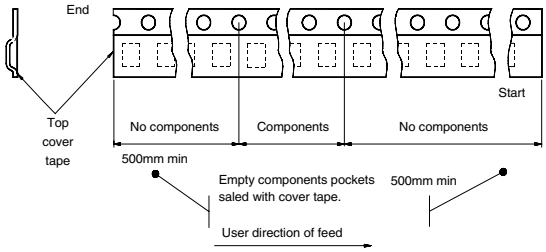
According to Electronic Industries Association (EIA) Standard 481 rev. A, Feb 1986

Tape width	**W**	16
Tape Hole Spacing	**P0 (± 0.1)**	4
Component Spacing	**P**	8
Hole Diameter	**D (± 0.1/-0)**	1.5
Hole Diameter	**D1 (min)**	1.5
Hole Position	**F (± 0.05)**	7.5
Compartment Depth	**K (max)**	6.5
Hole Spacing	**P1 (± 0.1)**	2



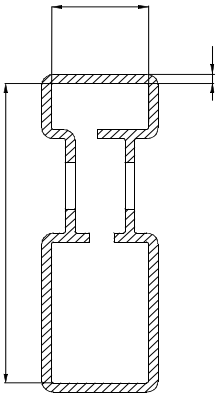
All dimensions are in mm.





5.5 IPAK packing information

Figure 33. IPAK tube shipment (no suffix)



Base Q.ty	75
Bulk Q.ty	3000
Tube length (± 0.5)	532
A	6
B	21.3
C (± 0.1)	0.6

All dimensions are in mm.

6 Revision history

Table 12. Document revision history

Date	Revision	Changes
Oct-1997	1	Initial release.
22-Aug-2006	2	Document restructured.
12-Dec-2008	3	Document restructured and reformatted. Added *ECOPACK® packages* information.
25-Sep-2013	4	Updated disclaimer.

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